

Surface Mount Glass Passivated Rectifier



DO-214AB (SMC)

FEATURES

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Solder dip 260 °C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



**RoHS
COMPLIANT**

TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters and freewheeling diodes for consumer, automotive and telecommunication.

MECHANICAL DATA

Case: DO-214AB (SMC)

Epoxy meets UL 94V-0 flammability rating

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test, HE3 suffix for high reliability grade (AEC Q101 qualified), meets JESD 201 class 2 whisker test

Polarity: Color band denotes cathode end

PRIMARY CHARACTERISTICS

| | |
|---------------------|----------------|
| I _{F(AV)} | 3.0 A |
| V _{RRM} | 50 V to 1000 V |
| I _{FSM} | 100 A |
| I _R | 10 µA |
| V _F | 1.15 V |
| T _J max. | 150 °C |

MAXIMUM RATINGS (T_A = 25 °C unless otherwise noted)

| PARAMETER | SYMBOL | S3A | S3B | S3D | S3G | S3J | S3K | S3M | UNIT |
|--|-----------------------------------|---------------|-----|-----|-----|-----|-----|------|------|
| Device marking code | | SA | SB | SD | SG | SJ | SK | SM | |
| Maximum recurrent peak reverse voltage | V _{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V _{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC blocking voltage | V _{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum average forward rectified current at T _L = 103 °C | I _{F(AV)} | 3.0 | | | | | | A | |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | I _{FSM} | 100 | | | | | | A | |
| Operating junction and storage temperature range | T _J , T _{STG} | - 55 to + 150 | | | | | | °C | |

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| PARAMETER | TEST CONDITIONS | SYMBOL | S3A | S3B | S3D | S3G | S3J | S3K | S3M | UNIT |
|---|---|----------|-----|-----|-----|------|-----|-----|-----|---------------|
| Maximum instantaneous forward voltage | 2.5 A | V_F | | | | 1.15 | | | | V |
| Maximum DC reverse current at rated DC blocking voltage | | I_R | | | | 10 | | | | μA |
| | $T_A = 25^\circ\text{C}$ | | | | | 250 | | | | |
| | $T_A = 125^\circ\text{C}$ | | | | | | | | | |
| Typical reverse recovery time | $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$ | t_{rr} | | | | 2.5 | | | | μs |
| Typical junction capacitance | 4.0 V, 1 MHz | C_J | | | | 60 | | | | pF |

 THERMAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| PARAMETER | SYMBOL | S3A | S3B | S3D | S3G | S3J | S3K | S3M | UNIT |
|---|------------------------------------|-----|-----|-----|-----|-----|-----|-----|--------------------|
| Typical thermal resistance ⁽¹⁾ | $R_{\theta JA}$ $R_{\theta JL}$ | | | | 47 | | | | $^\circ\text{C/W}$ |

Note:

(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3 x 0.3" (8.0 x 8.0 mm) copper pad area

ORDERING INFORMATION (Example)

| PREFERRED P/N | UNIT WEIGHT (g) | REFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE |
|---------------------------|-----------------|-----------------------|---------------|------------------------------------|
| S3J-E3/57T | 0.211 | 57T | 850 | 7" diameter plastic tape and reel |
| S3J-E3/9AT | 0.211 | 9AT | 3500 | 13" diameter plastic tape and reel |
| S3JHE3/57T ⁽¹⁾ | 0.211 | 57T | 850 | 7" diameter plastic tape and reel |
| S3JHE3/9AT ⁽¹⁾ | 0.211 | 9AT | 3500 | 13" diameter plastic tape and reel |

Note:

(1) Automotive grade AEC Q101 qualified

RATINGS AND CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

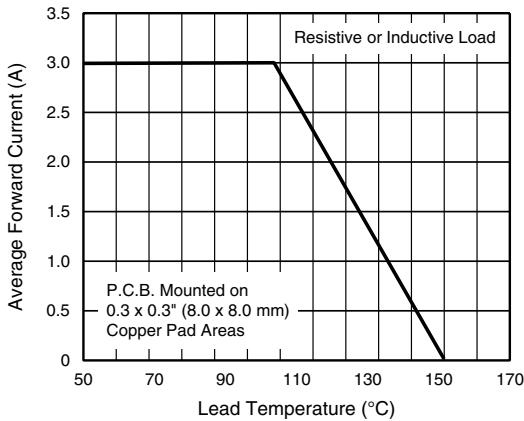


Figure 1. Forward Current Derating Curve

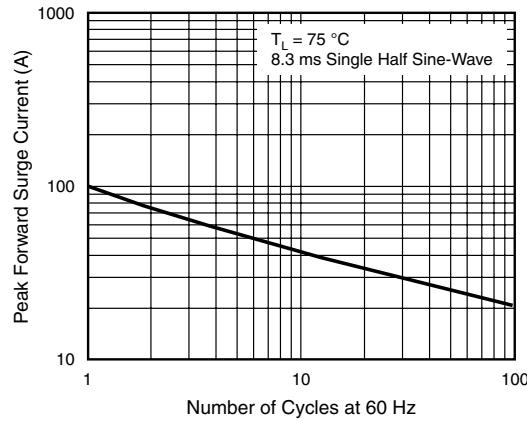


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

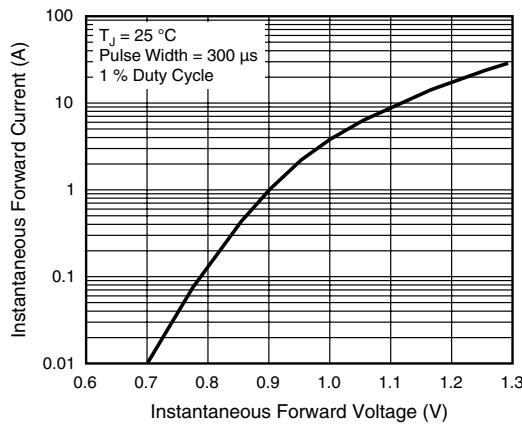


Figure 3. Typical Instantaneous Forward Characteristics

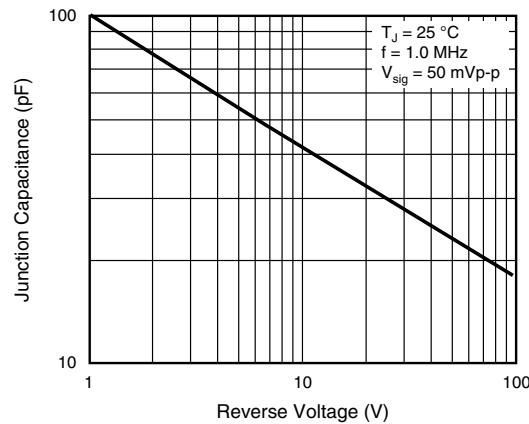


Figure 5. Typical Junction Capacitance

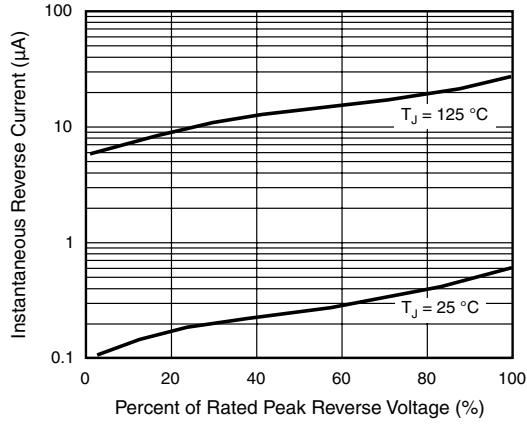


Figure 4. Typical Reverse Characteristics

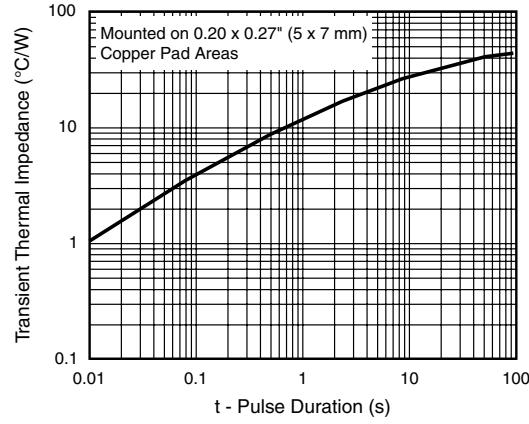
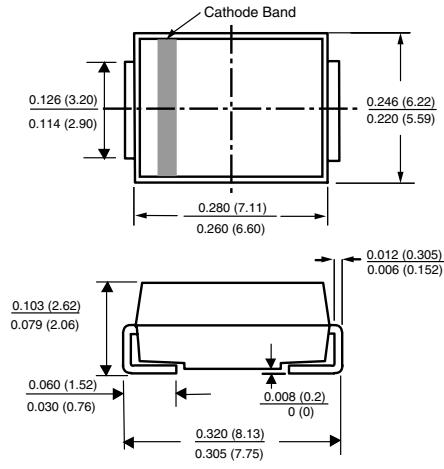


Figure 6. Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214AB (SMC)



Mounting Pad Layout

